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U.S. UTILITY Patent Application

12/18/01
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APPL NUM 10017384	FILING DATE 12/18/2001	CLASS 304 427	SUBCLASS 242	GAU 111 1762	EXAMINER VALENTINE
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204

**CONTINUING DATA VERIFIED:

THIS APPLICATION IS A DIV OF 09/674,179 10/27/2000, 6517,894

** FOREIGN APPLICATIONS VERIFIED:

JAPAN 10-136151 04/30/1998

JAPAN 10-136152 04/30/1998

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no
ATTORNEY DOCKET NO 2001-1846		
TITLE : Substrate plating method and apparatus		
U.S. DEPT. OF COMM./PAT. & TM-PTO-435L (Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner		
		PREPARED FOR ISSUE		
		Application Examiner		
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